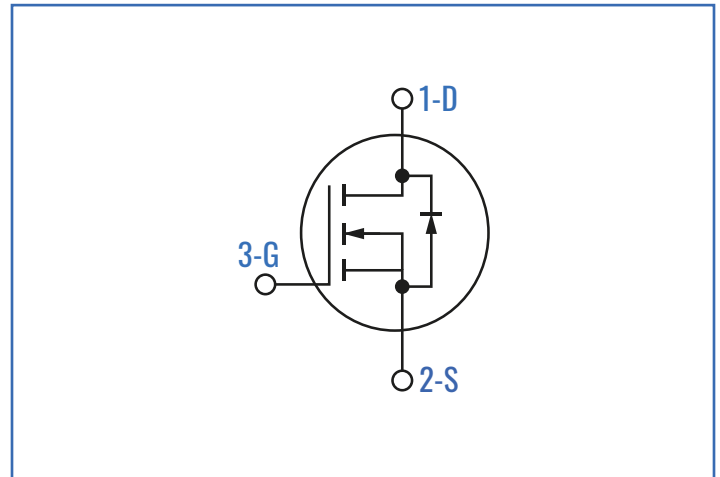


### KEY FEATURES

- $I_D$  15A
- $R_{DS(on)}$  760m $\Omega$
- FAST RECOVERY DIODE
- AVALANCHE RATED
- TO-258 HERMETIC PACKAGE
- BACKSIDE ISOLATION
- JANTX, JANTXV SCREENING AVAILABLE



### ORDERING GUIDE

**Part Number** SMF404  
**Description** 1000V N-Channel Power MOSFET

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ unless otherwise specified)

PARAMETER	SYMBOL	VALUE	TEST CONDITIONS
Drain-Source Voltage	$V_{DSmax}$	1000V	$V_{GS} = 0V, I_D = 100\mu A$
Gate-Source Voltage (dynamic)	$V_{GSM}$	$\pm 30V$	Transient
Gate-Source Voltage	$V_{GSS}$	$\pm 20V$	Continuous
Drain Current, continous	$I_{D25}$	15A	$T_C = 25^\circ\text{C}$
Drain Current, pulsed	$I_{D(PULSE)}$	40A	Pulse width $T_p$ limited by $T_{Jmax}$
Power Dissipation	$P_D$	280W	$T_C = 25^\circ\text{C}$
Junction Temperature Range, Operating	$T_J$	-55 $^\circ\text{C}$ to 150 $^\circ\text{C}$	
Junction Temperature Range, Storage	$T_{STG}$		

**ELECTRICAL SPECIFICATIONS ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Min.	Typ.	Max.	Unit	
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 1mA$	$V_{(BR)DSS}$	1000		V	
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 1mA, T_J = 25^\circ\text{C}$	$V_{GS(th)}$	3.5	6.5	V	
Off -State Drain Current	$V_{DS} = 1000V, V_{GS} = 0V, T_J = 25^\circ\text{C}$ $V_{DS} = 1000V, V_{GS} = 0V, T_J = 125^\circ\text{C}$	$I_{DSS}$		25	$\mu\text{A}$	
				1	mA	
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	$I_{GSS}$		$\pm 100$	nA	
Drain-Source On-state Resistance	$V_{GS} = >20V, I_D = 7.5A, T_J = 25^\circ\text{C}$	$R_{DS(on)}$		760	900	m $\Omega$
Transconductance	$V_{DS} = >20V, I_D = 7.5A, T_J = 25^\circ\text{C}$	$G_{fs}$	6.5	8.5	S	
Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{GS} = 0V, V_{DS} = 25V, f = 100kHz$	$C_{iss}$ $C_{oss}$ $C_{rss}$		5140 322 43	pF	
Total Gate Charge Gate to Source Charge Gate to Drain Charge	$V_{GS} = 10V, V_{DS} = 0.5 \times V_{DSS}, I_{DS} = 0.5 \times I_{D25}$	$Q_{g(on)}$ $Q_{gs}$ $Q_{gd}$		97 38 42	nC	
Turn On Delay Time Rx Time Turn Off Delay Time Fall Time	$V_{GS} = 10V, V_{DS} = 0.5 \times V_{DSS}, I_{DS} = 7.5 \times I_{D25}$ , $R_G = 2\Omega$ (external)	$t_{d(on)}$ $t_r$ $t_{d(off)}$ $t_f$		41 44 44 58	ns	
Thermal Resistance		$R_{thJC}$		0.445	$^\circ\text{C/W}$	

**BODY DIODE CHARACTERISTICS ( $T_J = 25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Min.	Typ.	Max.	Unit
Body Diode Forward Voltage	$I_F = I_S, V_{GS} = 0V, T_J = 25^\circ\text{C}$	$V_{SD}$		1.5	V
Body Diode Reverse Recovery Time	$V_r = 100V, V_{GS} = 0V, I_D = 7.5A, di/dt = 100A/\mu\text{s}$	$T_{rr}$		500	ns
Body Diode Reverse Recovery Charge	$I_F = 28A, di/dt = 100A/\mu\text{s}, V_r = 100V$	$Q_{RM}$	0.6		nC
Source to Drain Diode Current, cont.	$V_{GS} = 0V$	$I_S$		15	A
Pulse Diode Forward Current	Repetitive, pulse width limited by $T_{JM}$	$I_{SM}$		60	A

#### TYPICAL PERFORMANCE

Fig. 1 Maximum Power Dissipation vs. Case Temperature

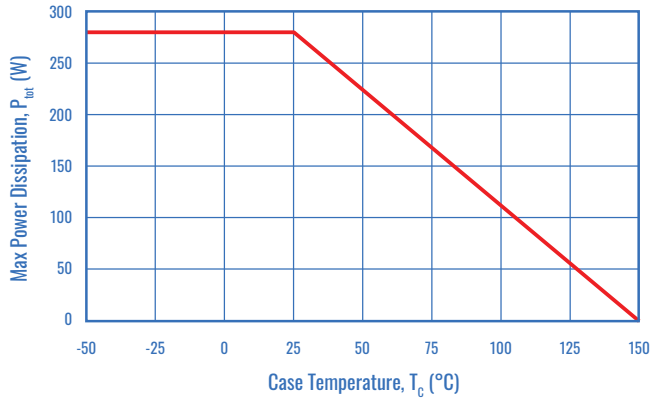


Figure 2. MOSFET Junction to case Transient Thermal Impedance, Z<sub>th Jc</sub> (°C/W)

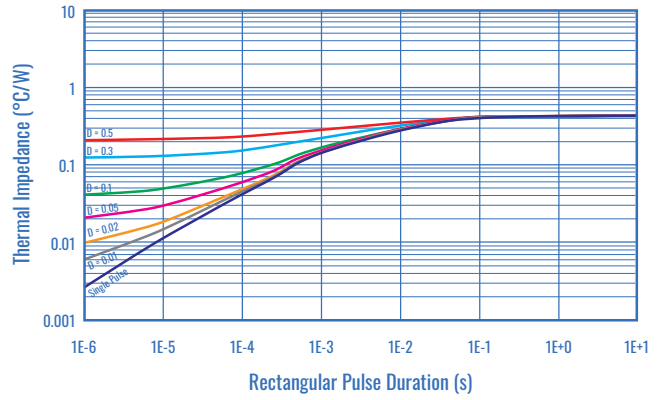
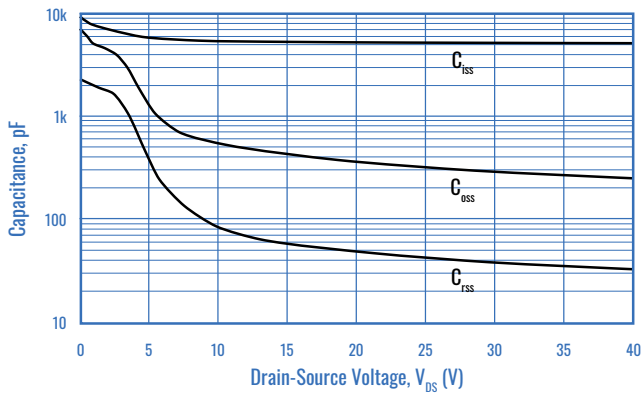
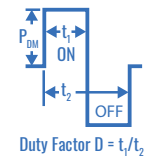


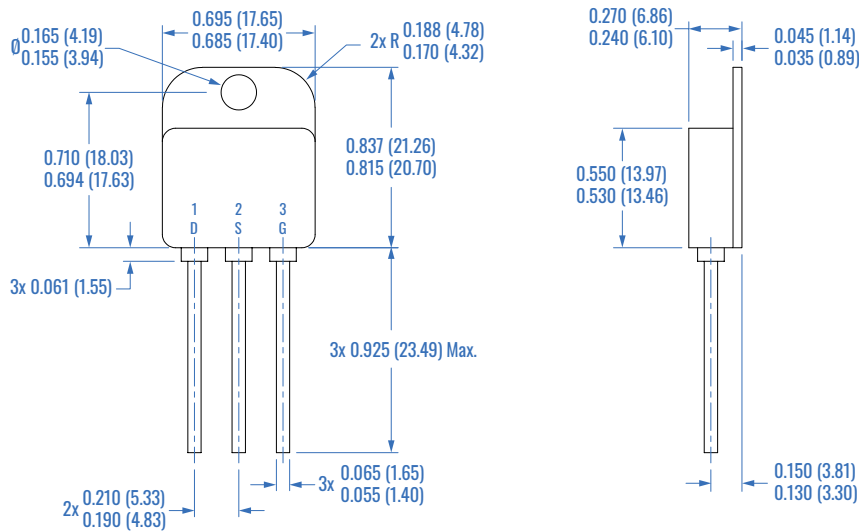
Figure 3. Capacitance vs Drain-Source Voltage



$$T_{j(PK)} = (P_{DM} \times Z_{thJC}) + Z_c$$



#### OUTLINE DIMENSION



All dimensions in inches (mm) maximum minimum

#### SCHEMATIC

